



## Material Content Data Sheet



<b>Sales Product Name</b>		TLS810B1EJ V50		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001839790						
<b>Package</b>		PG-DSO-8-52		<b>Weight*</b>		83.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.996	1.19	1.19	11902	11902
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8696	
wire	non noble metal	copper	7440-50-8	29.548	35.31	36.23	353101	362341
	non noble metal	copper	7440-50-8	0.048	0.06	0.06	570	570
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1207
plastics	plastics	epoxy resin	-	4.647	5.55		55528	
	inorganic material	silicondioxide	60676-86-0	45.759	54.68	60.35	546834	603569
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8307	8307
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8658	8658
glue	plastics	epoxy resin	-	0.097	0.12		1163	
	noble metal	silver	7440-22-4	0.292	0.35	0.47	3490	4653
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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